

Claims:

1. A semiconductor wafer container including two outer shells in a substantially flat and identical form, each outer shell vertically overlapping so as to accommodate a single semiconductor wafer therein,

wherein each outer shell has a main body, a wafer retaining device and an external wall forming device,

wherein the wafer retaining device accommodates and fixedly holds the wafer in such a manner that upper and bottom surfaces of the wafer are not substantially in contact with the outer shells, the wafer retaining device including: an inclined surface formed on an upper surface of the outer shell and being in line contact with an outer peripheral edge of the wafer from below; a wafer contact surface formed on a bottom surface of the outer shell and being in surface contact with the outer peripheral edge of the wafer from above; and a shallow gap portion formed on each central region of both the upper and bottom surfaces of the outer shell so as to cover an upper part or a lower part of the wafers; and

wherein the external wall forming device has a hanging portion formed on an outer peripheral edge of the bottom surface of the outer shell so as to externally constitute a closed external wall relative to the wafer when each outer shell vertically overlaps to store the wafer,

wherein the outer shell further has a positioning device, the positioning device being a boss and a boss hole engageable with each other and being provided on a surface of the outer shell in a position linearly symmetrical with a line crossing a center of the outer shell.

wherein the boss of one outer shell allows engagement with the boss hole of the other outer shell when each outer shell vertically overlaps.

wherein the semiconductor wafer container has an external form to be plane-symmetrical with respect to the wafer accommodated in the container when each outer shell is vertically positioned and when an upper outer shell thereof is reversed upside down and overlaps a lower outer shell, and

wherein the boss and the boss hole are arranged on each upper and bottom surface of the outer shell in which to allow engagement of the boss of one outer shell with the boss hole of the other outer shell when the upper outer shell is reversed upside down and overlaps the lower outer shell.

2. The semiconductor wafer container according to claim 1, wherein each upper surface of the outer shells has four inclined surfaces equally spaced.
3. The semiconductor wafer container according to claim 1, wherein a contact width at the wafer contact surface relative to the outer peripheral edge of the semiconductor wafer is within a range of 0.5 mm and 1.5 mm.
4. The semiconductor wafer container according to claim 2, wherein a contact width at the wafer contact surface relative to the outer peripheral edge of the semiconductor wafer is within a range of 0.5 mm and 1.5 mm.